L Number	Hits	Search Text	DB	Time stamp
2	165	((((((((((conduct\$3 near5 foil) or ((copper	USPAT;	2004/03/31 12:04
-		aluminum) near5 (film sheet))) and pattern\$3	US-PGPUB	
) and (insulat\$3 dielectric)) and etch\$3)		
		and (trench recess open\$3 hole groove)) and		
		(semiconductor wafer substrate)) and (copper		
		Cu aluminum Al (iron?nickel (iron near3		
		nickel)))) and (PR photoresist resist		
		photo?resist)) and resin) and ((electoless		!
		near3 plat\$3) electo?plat\$3 (electro near3	1	
		plat\$3))		
3	0	(((((((((conduct\$3 near5 foil) or ((copper	EPO; JPO;	2004/03/31 12:04
	· ·	aluminum) near5 (film sheet))) and pattern\$3	DERWENT;	2004/03/31 12:04
) and (insulat\$3 dielectric)) and etch\$3)	IBM TDB	
i l		and (trench recess open\$3 hole groove)) and	1511_155	
		(semiconductor wafer substrate)) and (copper		!
		Cu aluminum Al (iron?nickel (iron near3		
		nickel)))) and (PR photoresist resist		
		photo?resist)) and resin) and ((electoless		
		near3 plat\$3) electo?plat\$3 (electro near3		
		plat\$3))		
4	12105	(((((conduct\$3 near5 foil) or ((copper	USPAT;	2004/03/31 12:05
•	12105	aluminum) near5 (film sheet))) and pattern\$3	US-PGPUB	2004/03/31 12:03
) and (insulat\$3 dielectric)) and (trench	US-FGF0B	
		recess open\$3 hole groove)) and resin		
5	288	(((((conduct\$3 near5 foil) or ((copper	EPO; JPO;	2004/03/31 12:05
	200	aluminum) near5 (film sheet))) and pattern\$3	DERWENT;	2004/03/31 12:03
) and (insulat\$3 dielectric)) and (trench	IBM TDB	
,		recess open\$3 hole groove)) and resin	15.1_155	
6	38		USPAT;	2004/03/31 12:06
	30	trench)	US-PGPUB	2001, 03, 31 12.00
7	34	1	USPAT;	2004/03/31 12:08
'	J.	aluminum) near5 (film sheet))) and pattern\$3	US-PGPUB	2001, 03, 31 12.00
) and (insulat\$3 dielectric)) and (trench	00 10100	
		recess open\$3 hole groove)) and resin) and		
		(conductive near3 foil) and (isolat\$3 near5		i
		trench)		
8	38	1	USPAT;	2004/03/31 12:06
		trench)) ((((((conduct\$3 near5 foil) or	US-PGPUB	2001, 03, 31 12.00
		((copper aluminum) near5 (film sheet))) and	00 10102	
ŀ		pattern\$3) and (insulat\$3 dielectric)) and		
		(trench recess open\$3 hole groove)) and		
		resin) and (conductive near3 foil) and		
		(isolat\$3 near5 trench))		
9	n	((((((conduct\$3 near5 foil) or ((copper	EPO; JPO;	2004/03/31 12:08
-		aluminum) near5 (film sheet))) and pattern\$3	DERWENT;	2004,05/31 12.00
) and (insulat\$3 dielectric)) and (trench	IBM TDB	
		recess open\$3 hole groove)) and resin) and	100	
		(conductive near3 foil) and (isolat\$3 near5		[
		trench)		
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